Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model
[List multiple models if applicable.]

HP Pavilion Laptop PC 17

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm M/B</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries Main battery</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>POWER CORD</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
Components, parts and materials containing radioactive substances

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 Screwdriver</td>
<td>#1, #0</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove rear rubber foot *2 pcs
2. Remove screw *10 pcs
3. Remove ODD module
4. Disassemble the base cover from chassis ass'y
5. Remove battery screw *4 pcs
6. Remove battery pack
7. Remove HDD module
8. Remove USB ffc from USB board connector
9. Remove USB board screw *1 pcs
10. Remove USB board
11. Remove Fan cable from MB connector
12. Remove Fan screw *3 pcs
13. Remove Fan module
14. Remove LVDS cable from MB connector
15. Remove speaker cable from MB connector
16. Remove touch pad ffc from MB connector
17. Remove keyboard membrane
18. Remove antenna cable from MB connector
19. Remove DC-in cable from MB connector
20. Remove MB screw *6 pcs
21. Remove MB
22. Remove speaker screw *1 pcs
23. Remove speaker
24. Remove touch pad module screw *3 pcs
25. Remove touch pad module
26. Remove hinge screw *4 pcs
27. Remove DC-in cable
28. Remove LCD module ass'y
29. Remove LCD bezel
30. Remove panel screw *4 pcs
31. Remove panel
32. Remove LVDS cable from panel connector
33. Remove hinge screw *8 pcs
34. Remove hinge
35. Remove LVDS cable from camera connector
36. Remove camera
37. Remove antenna AL-foil
38. Remove antenna

PSG instructions for this template are available at EL-MF877-01
3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

3.21 Total part disassembly

3.22 Remove battery module

3.23 Remove service door

N/A

3.24 LCD module set disassembly
3.25 Top case disassembly

3.26 Thermal module and mother board disassembly

3.27 Bottom case disassembly